

ISO/IEC 10373-3:2010-10 (E)

Identification cards - Test methods - Part 3: Integrated circuit cards with contacts and related interface devices

Contents		Page
Foreword		v
1	Scope	1
2	Normative references	1
3	Terms and definitions	2
4	General items applicable to the test methods	2
4.1	Test environment	2
4.2	Pre-conditioning	2
4.3	Selection of test methods	3
4.4	Default tolerance	3
4.5	Total measurement uncertainty	3
4.6	Conventions for electrical measurements	3
4.7	Apparatus	3
4.7.1	Apparatus for testing the integrated circuit cards with contacts (card-test-apparatus)	3
4.7.2	Apparatus for testing the interface device (IFD-test-apparatus)	8
4.7.3	Test Scenario	13
4.8	Relationship of test methods versus base standard requirements	13
5	Test methods for electrical characteristics of cards with contacts	16
5.1	VCC contact	16
5.1.1	Apparatus	16
5.1.2	Procedure	16
5.1.3	Test report	17
5.2	I/O contact	17
5.2.1	Apparatus	17
5.2.2	Procedure	17
5.2.3	Test report	19
5.3	CLK contact	19
5.3.1	Apparatus	19
5.3.2	Procedure	19
5.3.3	Test report	20
5.4	RST contact	20
5.4.1	Apparatus	20
5.4.2	Procedure	20
5.4.3	Test report	21
5.5	SPU (C6) contact	21
6	Test methods for logical operations of cards with contacts	21
6.1	Answer to Reset (ATR)	21
6.1.1	Cold Reset and Answer-to-Reset (ATR)	21
6.1.2	Warm Reset	22
6.2	T=0 Protocol	22
6.2.1	I/O transmission timing for T=0 protocol	22
6.2.2	I/O character repetition for T=0 protocol	23
6.2.3	I/O reception timing and error signaling for T=0 protocol	24
6.3	T=1 Protocol	25
6.3.1	I/O transmission timing for T=1 protocol	25
6.3.2	I/O reception timing for T=1 protocol	25

6.3.3	Character Waiting Time (CWT) behavior	26
6.3.4	card-reaction to IFD exceeding character waiting time (CWT)	27
6.3.5	Block Guard time (BGT)	27
6.3.6	Block sequencing by the card	28
6.3.7	Reaction of the card to protocol errors	31
6.3.8	Recovery of a transmission error by the card	31
6.3.9	Resynchronization	32
6.3.10	IFSD negotiation	33
6.3.11	Abortion by the IFD	34
7	Test methods for physical and electrical characteristics of the IFD	35
7.1	Activation of contacts	35
7.1.1	Apparatus	35
7.1.2	Procedure	35
7.1.3	Test report	35
7.2	VCC contact	36
7.2.1	Apparatus	36
7.2.2	Procedure	36
7.2.3	Test report	37
7.3	I/O contact	37
7.3.1	Apparatus	37
7.3.2	Procedure	37
7.3.3	Test report	39
7.4	CLK contact	39
7.4.1	Apparatus	39
7.4.2	Procedure	39
7.4.3	Test report	41
7.5	RST contact	41
7.5.1	Apparatus	41
7.5.2	Procedure	41
7.5.3	Test report	42
7.6	SPU (C6) contact	42
7.7	Deactivation of the contacts	42
7.7.1	Apparatus	42
7.7.2	Procedure	42
7.7.3	Test report	43
8	Test methods for logical operations of the IFD	43
8.1	Answer to Reset (ATR)	43
8.1.1	Card Reset (cold reset)	43
8.1.2	card Reset (warm reset)	43
8.2	T=0 Protocol	44
8.2.1	I/O transmission timing for T=0 protocol	44
8.2.2	I/O character repetition for T=0 protocol	44
8.2.3	I/O reception timing and error signaling for T=0 protocol	45
8.3	T=1 Protocol	46
8.3.1	I/O transmission timing for T=1 protocol	46
8.3.2	I/O reception timing for T=1 protocol	47
8.3.3	IFD Character Waiting Time (CWT) behavior	48
8.3.4	IFD-reaction to card exceeding CWT	49
8.3.5	Block Guard time (BGT)	49
8.3.6	Block sequencing by the IFD	50
8.3.7	Recovery of a transmission error by the IFD	52
8.3.8	IFSC negotiation	53
8.3.9	Abortion by the card	53
8.4	IFD -- Reaction of the IFD to invalid PCBs	54
8.4.1	Apparatus	54
8.4.2	Procedure	54
8.4.3	Test report	55